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AMENDMENT HISTORY

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GENERAL DESCRIPTION

TM52-F2384 is a version of a new, fast 8051 architecture for an 8-bit microcontroller single chip with an instruction set fully compatible with industry standard 8051, C language development platform, and retains most 8051 peripheral's functional block. Typically, the **TM52-F2384** executes instructions six times faster than the standard 8051 architecture.

The **TM52-F2384** provides improved performance, lower cost and fast time-to-market by integrating features on the chip, including 16K Bytes MTP program memory, 128 Bytes EEPROM, 1024 Bytes SRAM, Low Voltage Reset (LVR), Low Battery Detector (LBD), dual clock power saving operation mode, SPI Interface, Master I2C Interface, 8051 standard UART and Timer0/1/2, adjustable real time clock Timer3, LCD/LED Driver, Touch Key, 12-bit SAR ADC, 6 set 8-bit PWM, Resistance to Frequency Converter (RFC) and Watchdog Timer. Its high reliability and low power consumption feature can be widely applied in consumer, industry and home appliance products.

BLOCK DIAGRAM

FEATURES

1. Standard 8051 Instruction set, fast machine cycle

Executes instructions six times faster than the standard 8051.

2. 16K Bytes MTP Program Memory

- Support "In Circuit Programming" (ICP) or "In System Programming" (ISP) for the MTP code
- Support Byte Write "In Application Programming" (IAP) mode.
- 10000 write cycles & 10 years data retention

3. 128 Bytes EEPROM

• 50,000 write cycles & 10 years data retention

4. Total 1280 Bytes SRAM (IRAM + XRAM)

- 256 Bytes IRAM in the 8051 internal data memory area
- 1024 Bytes XRAM in the 8051 external data memory area (accessed by MOVX Instruction)

5. Five System Clock type Selections

- Fast clock from Internal Fast RC (FRC, 14.7456 MHz)
- Fast clock from Internal Medium RC (MRC, 6MHz $@V_{DD} = 3V$, 2.3MHz $@V_{DD} = 1.5V$)
- Fast clock from External RC (RFC)
- Slow clock from Slow Crystal (SXT, 32768Hz)
- Slow clock from Internal Slow RC (SRC, 75KHz $@V_{DD} = 3V$, 35KHz $@V_{DD} = 1.5V$)
- System Clock can be divided by $1/2/4/16$ option

6. 8051 Standard Timer – Timer0 / 1 / 2

- 16-bit Timer0, also supports RFC or SXT/16 clock input counting
- 16-bit Timer1, also supports SXT/16 clock input counting
- 16-bit Timer2, also supports SXT/16 clock input counting

7. 23-bit Timer3 used for Real Time 32768Hz Crystal counting

- \bullet \pm 0.5 ppm \sim 61 ppm interrupt rate adjustable
- MSB 8-bit overflow auto-reload
- \bullet 16ms ~1.0 sec or overflow Interrupt

8. 10-Channel Touch Key

9. 12-bit SAR ADC

10. Resistance to Frequency Converter (RFC)

- RFC can be used for Temperature or Humidity sensor
- RFC clock can be used as System clock source

11. 8051 Standard UART

- Support One Wire UART
- Extra Baud rate generator
- Can use P3.0/P3.1 or P1.2/1.3 pins

12. SPI Interface

- Master or Slave mode selectable
- Programmable transmit bit rate
- Serial clock phase and polarity options
- MSB-first or LSB-first selectable

13. Master I2C Interface

14. 14-Sources, 4-level priority Interrupt

- Timer0 / Timer1 / Timer2 / Timer3 Interrupt
- INT0 / INT1 Falling-Edge / Low-Level Interrupt
- Pin Change Interrupt
- P2.7 (INT2) Interrupt
- SPI / I2C / UART Interrupt
- Touch Key / ADC Interrupt
- PWM5 Interrupt
- LBD Interrupt

15. Pin Interrupt can Wake up CPU from Power-Down (Stop) mode

- \bullet P3.2 / P3.3 / P2.7 (INT0 / INT1 / INT2) Interrupt & Wake-up
- Port $1/2/3$ pin can be defined as Interrupt & Wake-up pin (by pin change)

16. Max. 40 Programmable I/O pins

- CMOS Output
- Pseudo-Open-Drain, or Open-Drain Output
- Schmitt Trigger Input
- Pin Pull-up can be Enabled or Disabled

17. LCD Controller / Driver

- $1/3 \sim 1/8$ Duty
- \bullet 4 COM x 44 SEG ~ 8 COM x 40 SEG selectable
- \bullet 1/3 LCD Bias voltage, VL1 = VLCD/3, VL2 = VLCD*2/3, VL3 = VLCD
	- PUMP=0: VLCD (VL3) = $V_{BAT}*3/5 \sim V_{BAT}*5/5$ (16 steps Brightness level)
	- \triangleright PUMP=1: VLCD (VL3) = V_{BAT}*1.2 ~ V_{BAT}*2 (16 steps Brightness level)
- 1/2 LCD Bias voltage, PUMP=1: VL1 = V_{BAT} , VL2 = VLCD = V_{BAT} *2
- Frame Rate: 40~90Hz

18. LED Controller / Driver

- \bullet Max. 8 COM x 36 SEG
- 60 mA High Sink COM, Active Low
- Dot Matrix Mode (DMX), up to $8 \times 7 = 56$ dots

19. BandGap Voltage Reference for Low Battery Detection (LBD)

• Detect V_{BAT} voltage level from 1.8V to 3.7V

20. Built-in tiny current LDO Regulator for chip internal power supply (V_{DD})

- V_{DD} voltage level can be set to $0.375*V_{BAT} \sim 0.725*V_{BAT}$ for power saving
- Must set $V_{DD} > 1.4V$

21. Watch Dog Timer based on Slow Clock

22. CRC Code check

23. 6 set 8-bit PWM

- Adjustable Period & Clock Pre-scale
- PWM0P / PWM0N support Pump Voltage Drive
- PWM1 with 300mA sink current capability
- PWM5 can generate Interrupt

24. Five types Reset

- Power on Reset (1.1V or 1.7V)
- Selectable External Pin Reset
- Selectable Watch Dog Reset
- Software Command Reset
- Low Voltage Reset (LVR, $1.7V \sim 3.6V$)

25. Five types Operation Mode

• Fast / Slow / Idle / Halt / Stop mode

26. On-chip Debug / ICE interface

Use P1.2 / P1.3 pin, share with ICP programming pin

27. Operating Voltage and Current

- $V_{BAT} = 1.7V$ ~ 5.5V (25 °C) (> 2V for ADC, >3V for EEPROM)
- Total 3.2uA Halt mode Current with LCD on $\omega V_{BAT} = 3V$, $V_{DD} = 1.5V$

28. Operating Temperature Range

 $-40^{\circ}C - 105^{\circ}C$

29. 64/48 pin LQFP Package, 48-QFN Package

PIN ASSIGNMENT

Note: SEG44~47 only support LCD mode, does not support LED mode. *Note*: For low power application, all digital IOs (including unbounded or unused) should avoid high-impedance settings.

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DIE PAD LIST

Note: VDDA and VBAT need bonding together

Note: VSSI, VSSA and VSS need bonding together

Note: The two P35 PADs are connected inside chip, double bond for high sink application

PIN DESCRIPTION

Note: Digital I/O pins voltage swing from V_{SS} to V_{BAT} .

Note: P1.0~P1.7, P2.4~P2.5, P3.0~P3.1 and P3.4~P3.7 support Pin Change Interrupt & Wake-up

FUNCTIONAL DESCRIPTION

1. CPU Core

In the 8051 architecture, the C programming language is used as a development platform. The TM52 device features a fast 8051 core in a highly integrated microcontroller, allowing designers to be able to achieve improved performance compared to a classic 8051 device. TM52 series microcontrollers provide a complete binary code with standard 8051 instruction set compatibility, ensuring an easy migration path to accelerate the development speed of system products. The CPU core includes an ALU, a program status word (PSW), an accumulator (ACC), a B register, a stack point (SP), DPTRs, a program counter, an instruction decoder, and core special function registers (SFRs).

1.1 Accumulator (ACC)

This register provides one of the operands for most ALU operations. Accumulators are generally referred to as A or Acc and sometimes referred to as Register A. In this document, the accumulator is represented as "A" or "ACC," including the instruction table. The accumulator, as its name suggests, is used as a general register to accumulate the intermediate results of a large number of instructions. The accumulator is the most important and frequently used register to complete arithmetic and logical operations. It holds the intermediate results of most arithmetic and logic operations and assists in data transportation.

E0h.7~0 **ACC:** Accumulator

1.2 B Register (B)

The "B" register is very similar to the ACC and may hold a 1 Byte value. This register provides the second operand for multiply or divide instructions. Otherwise, it may be used as a scratch pad register. The B register is only used by two 8051 instructions, MUL and DIV. When A is to be multiplied or divided by another number, the other number is stored in B. For MUL and DIV instructions, it is necessary that the two operands be in A and B.

F0h.7~0 **B:** B register

1.3 Stack Pointer (SP)

The SP register contains the Stack Pointer. The Stack Pointer is used to load the program counter into memory during LCALL and ACALL instructions and is used to retrieve the program counter from memory in RET and RETI instructions. The stack may also be saved or loaded using PUSH and POP instructions, which also increment and decrement the Stack Pointer. The Stack Pointer points to the top location of the stack.

81h.7~0 **SP:** Stack Point

1.4 Dual Data Pointer (DPTRs)

TM52 device has two DPTRs, which share the same SFR address. Each DPTR is 16 bits in size and consists of two registers: the DPTR high byte (DPH) and the DPTR low byte (DPL). The DPTR is used for 16-bit-address external memory accesses, for offset code byte fetches, and for offset program jumps. Setting the DPSEL control bit allows the program code to switch between the two physical DPTRs.

82h.7~0 **DPL:** Data Point low byte

83h.7~0 **DPH:** Data Point high byte

F8h.0 **DPSEL:** Active DPTR Select

1.5 Program Status Word (PSW)

This register contains status information resulting from CPU and ALU operations. The instructions that affect the PSW are listed below.

A "0" means the flag is always cleared, a "1" means the flag is always set and an "X" means that the state of the flag depends on the result of the operation.

D0h.7 **CY:** ALU carry flag

D0h.6 **AC:** ALU auxiliary carry flag

D0h.5 **F0:** General purpose user-definable flag

- D0h.4~3 **RS1, RS0:** The contents of (RS1, RS0) enable the working register banks as:
	- 00: Bank 0 (00h~07h)
	- 01: Bank 1 (08h~0Fh)
	- 10: Bank 2 (10h~17h)
	- 11: Bank 3 (18h~1Fh)
- D0h.2 **OV:** ALU overflow flag
- D0h.1 **F1:** General purpose user-definable flag
- D0h.0 **P:** Parity flag. Set/cleared by hardware each instruction cycle to indicate odd/even number of "one" bits in the accumulator.

2. Memory

2.1 Program Memory

The chip has a 16K Bytes MTP program memory, which can support In Circuit Programming (ICP), In Application Programming (IAP) and In System Programming (ISP) function modes. The MTP write endurance is at least 10000 cycles. The program memory address continuous space (0000h~3FFFh) is partitioned to several sectors for device operation.

2.1.1 Program Memory Functional Partition

The last 16 bytes (3FF0h~3FFFh) of program memory is defined as reserve area or chip Configuration Word (CFGWs). Three of them are loaded into the device control registers upon power on reset (POR). The 0000h~007Fh is occupied by Reset/Interrupt vectors as standard 8051 definition. In the in-circuit emulation (ICE) mode, address space 2D00h~2FFFh is reserved for ICE System communication.

2.1.2 MTP ICP Mode

The MTP memory can be programmed by the tenx proprietary writer (TWR99/TWR100), which needs at least four wires (VBAT, VSS, P1.2, and P1.3 pins) to connect to this chip. If the user wants to program the MTP memory on the target circuit board (In Circuit Program, ICP), these pins must be reserved sufficient freedom to be connected to the Writer.

2.1.3 MTP IAP Mode

The chip has "In Application Program" (IAP) capability, which allows software to read/write data from/to the MTP memory during CPU run time as conveniently as data EEPROM access. The IAP function is byte writable, meaning that the chip does not need to erase one MTP page before write. The full MTP space is available for IAP access, except the CFGWH (address 3fffh).

2.1.4 IAP Mode Access Routines

MTP IAP Write is simply achieved by a "MOVX @DPTR, A" instruction while the DPTR contains the target MTP address (0~3FFEh), and the ACC contains the data being written. The chip accepts MTP write command only when MTPWE=1. MTP IAP writing requires approximately 1ms. Meanwhile, the CPU stays in a waiting state, but all peripheral modules (Timers, LCD, and others) continue running during the writing time. The software must handle the pending interrupts after an IAP write. The chip has a build-in IAP Time-out function for escaping write fail state.

MTP IAP writing needs higher VDD voltage and lower F_{SYSCLK} , typically VDD>4.0V and F_{SYSCLK} < 8MHz. Besides, S/W must disable WDT and enable LVR before IAP Write. Be careful to avoid the IAP write during VDD drops. It is recommended to insert at least 20uS delay between each write for the consecutive writing.

Because the Program memory and the IAP data space share the same entity, a **MTP IAP Read** can be performed by the "MOVX A, @DPTR" or "MOVC" instruction as well. A MTP IAP read does not require extra CPU wait time.

; IAP example code, need VDD > 4.0V & WDT disable

2.2 EEPROM

The chip contains 128 bytes of data EEPROM memory. It is organized as a separate data space, in which single bytes can be read and written. The EEPROM has an endurance of at least 50K write cycles.

(Only even addresses can be used, odd addresses are invalid)

The EEPROM Write is similar to the MTP IAP mode. It is simply achieved by a "MOVX @DPTR, A" instruction while the DPTR contains the target EEPROM address (EE00h~EEFEh, ADDR=ADDR+2), and the ACC contains the data being written. EEPROM writing requires approximately 2 ms $\omega_{\text{Ba}T} = 3V$, 1 ms $@V_{BAT}=5V$. Meanwhile, the CPU stays in a waiting state, but all peripheral modules (Timers, LED, and others) continue running during the writing time. The software must handle the pending interrupts after an EEPROM write. The chip has a build-in EEPROM Time-out function shared with MTP IAP for escaping write fail state.

EEPROM writing needs higher VDD voltage, typically VDD > 3.0V. Besides, S/W must disable WDT and enable LVR before EEPROM Write. Be careful to avoid the EEPROM write during VDD drops. It is recommended to insert at least 20uS delay between each write for the consecutive writing.

The EEPROM Read can be performed by the "MOVX A, @DPTR" instruction as long as the target address points to the EE00h~EEFEh area. The EEPROM read require approximately 300ns.

; EEPROM example code, need V_{DD} > 3.0V & WDT disable

97h.7~0 **MTPALL (W):** Write 65h to set MTPALL flag and enable MTP IAP; Write other value to clear MTPALL flag and disable IAP. It is recommended to clear it immediately after IAP access.

97h.0 **MTPALL (R):** Flag indicates MTP memory can be accessed by IAP or not.

C9h.7~0 **IAPWE (W):** Write 47h to set MTPWE control flag; Write E2h to set EEPWE control flag; Write other value to clear MTPWE and EEPWE flag. It is recommended to clear it immediately after MTP or EEPROM write.

C9h.7 **MTPWE (R):** Flag indicates MTP memory can be written by IAP or not, 1 = MTP write enable.

C9h.6 **IAPTO (R):** MTP (or EEPROM) write Time-Out flag, Set by H/W when MTP (or EEPROM) write Time-out occurs. Cleared by H/W when MTPWE=0 (or EEPWE=0).

C9h.5 **EEPWE (R):** Flag indicates EEPROM memory can be written or not, 1 = EEPROM write enable.

SFR D3h	Bit 7	Bit \circ	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
AUX2	ADC P07	P ₂₀ ADC	DOTTCC _	BDEDGE	VBGE	T TET B(T		IAPTE
R/W	R/W		W R/	W R	/W		R/W	
Reset								

D3h.1~0 **IAPTE:** MTP (or EEPROM) write time-out enable.

00: Disable

01: wait 1ms to trigger time-out flag, and escape the write fail state

10: wait 4ms to trigger time-out flag, and escape the write fail state

11: wait 8ms to trigger time-out flag, and escape the write fail state

2.3 Data Memory

As the standard 8051, the chip has both Internal and External Data Memory space. The Internal Data Memory space consists of 256 Bytes IRAM and SFRs, which are accessible through a rich instruction set. The External Data Memory space consists of 1024 Bytes XRAM, LCDRAM and IAP area, which can be only accessed by MOVX instruction.

2.3.1 IRAM

IRAM is located in the 8051 internal data memory space. The whole 256 Bytes IRAM are accessible using indirect addressing but only the lower 128 Bytes are accessible using direct addressing. There are four directly addressable register banks (switching by PSW), which occupy IRAM space from 00h to 1Fh. The address 20h to 2Fh 16 Bytes IRAM space is bit-addressable. IRAM can be used as scratch pad registers or program stack.

2.3.2 XRAM

XRAM is located in the 8051 external data memory space (address from FC00h to FFFFh). The 1024 Bytes XRAM can be only accessed by "MOVX" instruction.

2.3.3 SFRs

All peripheral functional modules such as I/O ports, Timers and UART operations for the device are accessed via Special Function Registers (SFRs). These registers occupy upper 128 Bytes of direct Data Memory space locations in the range 80h to FFh. There are 15 bit-addressable SFRs (which means that eight individual bits inside a single byte are addressable), such as ACC, B register, PSW, TCON, SCON, and others. The remaining SFRs are only byte addressable. SFRs provide control and data exchange with the resources and peripherals of the device. The TM52 series of microcontrollers provides complete binary code with standard 8051 instruction set compatibility. Beside the standard 8051 SFRs, the chip implements additional SFRs used to configure and access subsystems such as the SPI/LCD, which are unique to the chip.

3. Power Management

VBAT pin is the power supply of this chip. It provides voltage source to the built-in tiny current LDO Regulator for device internal operation. The VDD pin is the LDO output, which needs an external 1uF capacitor connection to VSS for voltage level stability. If IVCS=0, LDO is disable and VDD is shorted to VBAT. If IVCS=1, LDO is enable and the V_{DD} voltage level is defined by VDDSET SFR. The V_{DD} range can be set as V_{BAT} *0.375~ V_{BAT} *0.725. The lower V_{DD} voltage level causes lower chip current consumption, but user must also consider the System clock rate. Higher clock rate requires higher V_{DD} voltage level. User must keep $V_{DD}>1.4V(25^{\circ}C)$ for the chip's proper operation. In EEPROM write mode, user also needs to set $V_{DD}>3V(25°C)$.

The 1.2V BandGap Voltage Reference module supports for Low Battery Detection (LBD) and LVR. User can refer to the V_{BAT} voltage level for setting the V_{DD} level by VDDSET SFR. The BandGap and LBD consume un-neglect current, so user should not use them too often. Since V_{BAT} voltage level changes very slowly, user can detect it once an hour or once a day to reduce current consumption.

CFh.7 **PWRSAV2:** Power saving mode control

0: No power saving

1: Reduce Slow mode current consumption

C3h.7 **LBDO:** Low Battery Detector flag

If V_{BAT} < LBDSEL's setting voltage, LBDO=1; otherwise LBDO=0.

95h.7 **LBDIF:** LBD Interrupt Flag

Set by H/W at LBDO's rising or falling edge. Cleared by H/W when CPU vectors into the interrupt service routine. S/W writes 7Fh to INTFLG to clear this flag.

D3h.4 **LBDEDGE:** LBDIF trigger condition

0: LBDIF trigger by LBDO's rising edge. (when V_{BAT} falling)

1: LBDIF trigger by LBDO's falling edge. (when VBAT rising)

F5h.4~0 **VBGTRIM:** VBG adjustment. It is automatically loaded with MTP's 3FFBh data at power on reset and can be read/written as any other SFR register in normal mode. (00h=lowest)

4. Reset

The chip has five types of reset methods. The CFGW and SFRs control the Reset functionality.

4.1 Power on Reset (POR)

After Power on Reset, the chip stays on Reset state for 20ms as warm up time, then downloads the CFGWs register from MTP's last three words (other Reset dose not reload the CFGWs). The Power on Reset needs V_{BAT} voltage first discharge to near V_{SS} level, then rise beyond 1.0V or 1.7V, which is determined by the CFGWH. POR is disabled in Stop mode and enabled in others mode by VCON SFR control.

4.2 External Pin Reset

External Pin Reset is active low. The RSTn pin needs to keep at least 2 SRC clock cycle long to be sampled by the chip. Pin Reset can be disabled or enabled by CFGWH.

4.3 Software Reset

Software Reset is activated by writing the SFR 97h with data 56h.

4.4 Watch Dog Timer Reset

WDT overflow Reset is disabled or enable by WDTCON SFR. The WDT uses slow clock as its counting time base. WDT overflow speed is defined by WDTPSC SFR. WDT is cleared by the chip Reset or CLRWDT SFR bit.

4.5 Low Voltage Reset (LVR)

LVR is disabled or enable by VCON SFR. There are 16-level LVR can be selected by LVRSEL.

3FFFh.6 **XRSTE:** Pin Reset enable, 1=enable.

3FFFh.2 **AGMOD:** Power on reset level select.

0: POR is 1.7V

1: POR is 1.1V

97h.7~0 **SWRST (W):** Write 56h to generate S/W Reset.

F8h.3 **CLRWDT:** Set to 1 to clear Watch Dog Timer.

D2h.3~2 **WDTMOD:** WDT control

00: WDT disable

01: WDT disable in Halt / Stop mode, enable in Idle / Slow / Fast mode

10: WDT disable in Idle / Halt / Stop mode, enable in Slow / Fast mode

11: WDT disable in Stop mode, enable in Halt / Idle / Slow / Fast mode

D2h.1~0 **WDTPSC:** WDT pre-scalar time select

00: WDT overflow is 2048 Slow clock cycle (64ms @SXT=32K)

01: WDT overflow is 4096 Slow clock cycle (128ms @SXT=32K)

10: WDT overflow is 8192 Slow clock cycle (256ms @SXT=32K)

11: WDT overflow is 16384 Slow clock cycle (512ms @SXT=32K)

A7h.6 **PWRSAV:** Power saving mode control

0: No power saving

1: Power saving, disable POR in Halt mode, disable LVR/LBD in Idle/Halt/Stop mode, POR enable time is 1/16 duty.

A7h.5 **PORPD:** POR control, 1=force POR disable

A7h.4 **LBDPD:** LBD control, 1=force LBD disable

A7h.3 **LVRPD:** LVR control, 1=force LVR disable

5. Clock Circuitry & Operation Mode

5.1 System Clock

The chip is designed with dual-clock system. During runtime, user can directly switch the System clock from fast to slow or from slow to fast. It also can directly select a clock divider of 1, 2, 4 or 16. The Fast clock consists of FRC, MRC and RFC. The Slow clock can be selected as SXT or SRC. Fast mode and Slow mode are defined as the CPU running at Fast and Slow clock speeds. The five System Clock sources are list below.

FRC (Internal Fast RC, 14.7456 MHz $\omega V_{BAT} = 2.5V \sim 5.5V$): FRC is the default Fast clock type. Its frequency is controlled by FRCF SFR, which is automatically loaded with CFGW data at power on reset. The FRC is trimmed to 14.7456 MHz in chip manufacturing. FRC can maintain stable frequency when Temperature and V_{BAT} voltage change, but it needs higher V_{DD} voltage and consumes higher current.

MRC (Internal Medium RC, 6MHz $@V_{DD} = 3V$, 2.3MHz $@V_{DD} = 1.5V$): MRC frequency depends on V_{DD} voltage and differs chip by chip. The advantage of MRC is being able to work in lower V_{DD} voltage and consume lower current.

RFC (Resistance to Frequency Convert, External RC): RFC is usually used for RFC ADC measuring mode. Its frequency depends on External RC and V_{BAT} .

SRC (Internal Slow RC, 75KHz $@V_{DD} = 3V$, 35KHz $@V_{DD} = 1.5V$): After Reset, the chip is running at Slow mode with SRC clock. SRC can work in very low V_{DD} voltage and consumes very low current.

SXT (Slow Crystal, 32768Hz): SXT provides accurate real time base. It can work in very low V_{DD} voltage and consumes very low current.

The SXTKICK control bit can accelerate the Crystal start-up oscillating while $V_{BAT} < 1.5V$. To use this function, F/W needs to setup the LCD pump environment, which includes LCDPUMP=1, LCDCLK=10 (FASTCLK/128) and DSPON=1. After the Crystal oscillating becoming smooth, F/W must clear SXTKICK to reduce current consumption.

Before entering the Fast mode, S/W must select the Fast clock type in advance. If RFC is used as the Fast clock source, S/W also has to setup the pin mode and RFC related SFRs in advance.

Since Fast clock is useless in Slow mode, S/W can set STPFSUB=1 or STPRFC=1 to stop Fast Clock to reduce chip's current consumption. Before the chip switches to FRC, S/W must also consider the V_{DD} voltage level for chip operation safe range. The higher V_{DD} allows the chip to run at higher System Clock frequency. In typical condition, 16 MHz System Clock rate requires $V_{DD} > 2.5V$.

The CLKCON SFR controls the System clock operating. H/W automatically blocks the S/W abnormally setting for this register. S/W can only change the Slow clock type in Fast mode, and change the Fast clock type in Slow mode. Never to write both STPFSUB=1 $\&$ SELFCK=1 in FRC/MRC mode. It is recommended to write this register bit by bit.

Clock Structure

3FFDh MTP	The State $\overline{}$ B1t	\mathbf{r} . B1t б	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CFGFRC	$\hspace{0.1mm}-\hspace{0.1mm}$				FRCF			

3FFDh.6~0 **FRCF:** FRC frequency adjustment.

FRC is trimmed to 14.7456 MHz in chip manufacturing. FRCF records the trimming data.

F7h.6~0 **FRCF:** FRC frequency adjustment. It is automatically loaded with MTP's 3FFDh data at power on reset and can be read/written as any other SFR register in normal mode. So the FRC clock speed can be changed on CPU run time by S/W. (00h=lowest)

94h.7~6 **SXTGAIN:** 32768 SXT oscillator gain, 3=Highest gain, 0=Lowest gain. Higher gain can shorten the Crystal oscillation warm-up time. Lower gain can reduce oscillation current.

94h.5 **STPPCK:** Set 1 to stop UART/Timer0/Timer1/Timer2 clock in Idle mode for current reducing.

94h.4 **SXTKICK:** Set 1 to kick SXT by LCD pump voltage, for crystal start up $@V_{BAT} < 1.5V$

Note: In crystal mode, user should set the P0.7/P2.0 (SXT) pins as Input with Pull-up (section7).

Note: In the Power on stage, FW must wait until $V_{DD} > 2.2V$, before switch to FRC/1.

(*1) also need RFC related SFRs proper setting

5.2 Operation Modes

There are five operation modes for this chip. **Fast Mode** is defined as the CPU running at Fast clock speed. **Slow Mode** is defined as the CPU running at Slow clock speed. When the System clock speed is lower, the power consumption is lower.

Idle Mode is entered by setting the IDL bit in PCON SFR. Both Fast and Slow clock can be set as the System clock source in Idle Mode, but Slow clock is better for power saving. In Idle mode, the CPU puts itself to sleep while the on-chip peripherals stay active. The STPPCK bit can be set to furthermore reduce Idle mode current. If STPPCK=1, Timer0/1/2 and UART are stopped in Idle mode. The slower System clock rate also helps current saving. It can be achieved by setup the CLKPSC SFR to divide System clock frequency. Idle mode is terminated by Reset or enabled Interrupts wake up.

Halt Mode is entered by setting the PD bit in PCON SFR while STPSCK is cleared. Both Fast and Slow mode can switch to Halt mode. In Halt mode, all clocks stop except the Timer3, WDT, PWMs and LCD could be alive if they are enabled with Slow clock source. Halt mode is terminated by Reset, pin wake up or Timer3/PWM interrupt.

Stop Mode is entered by setting the PD bit in PCON SFR while STPSCK is set. This mode is the socalled "Power Down" mode in standard 8051. In Stop mode, all clocks stop. Stop Mode can be terminated by Reset or pin wake up.

87h.1 **PD:** Power down control bit, set 1 to enter Stop/Halt mode.

87h.0 **IDL:** Idle mode control bit, set 1 to enter Idle mode.

6. Interrupt & Wake-up

The chip has an 14-source four-level priority interrupt structure. All enabled Interrupts can wake up CPU from Idle mode, but only the Pin Interrupts can wake up CPU from Stop mode. The Halt mode can be waked up by Time3, PWM and Pin Interrupts. Each interrupt source has its own enable control bit. An interrupt event will set its individual Interrupt Flag, no matter whether its interrupt enable control bit is 0 or 1. The Interrupt vectors and flags are list below.

Vector	Flag	Description
0003	IE ₀	INTO external pin Interrupt (can wake up Stop/Halt mode)
000B	TF ₀	Timer ₀ Interrupt
0013	IE1	INT1 external pin Interrupt (can wake up Stop/Halt mode)
001B	TF1	Timer1 Interrupt
0023	$RI+TI$	Serial Port (UART) Interrupt
002B	$TF2+EXF2$	Timer2 Interrupt
0033		Reserved for ICE mode use
003B	TF3	Timer3 Interrupt (can wake up Halt mode)
0043	PNCIF	Pin change Interrupt (can wake up Stop/Halt mode)
004B	IE ₂	INT2 external pin Interrupt (can wake up Stop/Halt mode)
0053	TKIF+ADIF	Touch Key / ADC Interrupt
005B	SPIF+WCOL	SPI Interrupt
0063	LBDIF	LBD Interrupt
006B	PWMIF	PWM Interrupt (can wake up Halt mode)
0073	I2CIF	Master I2C Interrupt

Interrupt Vector & Flag

6.1 Interrupt Enable and Priority Control

The IE and INTE1 SFRs decide whether the pending interrupt is serviced by CPU. The P1WKUP and P3WKUP controls the individual Port1~3 pin's wake-up and interrupt capability. The IP, IPH, IP1 and IP1H SFRs decide the interrupt priority. An interrupt will be serviced as long as an interrupt of equal or higher priority is not already being serviced. If an interrupt of equal or higher level priority is being serviced, the new interrupt will wait until it is finished before being serviced. If a lower priority level interrupt is being serviced, it will be stopped and the new interrupt serviced. When the new interrupt is finished, the lower priority level interrupt that was stopped will be completed.

96h.7~0 **P1WKUP:** P1.7~P1.0 pin individual Wake-up / Interrupt enable control. 1=Enable

A1h.7~0 **P3WKUP:** P3.7~4, P2.5~4, P3.1~0 pin individual Wake-up / Interrupt enable control. 1=Enable

B9h.5, B8h.5 **PT2H, PT2 :** Timer2 Interrupt Priority control. (PT2H, PT2)=

- 11: Level 3 (highest priority)
- 10: Level 2
- 01: Level 1

00: Level 0 (lowest priority)

B9h.4, B8h.4 **PSH, PS :** Serial Port (UART) Interrupt Priority control. Definition as above.

B9h.3, B8h.3 **PT1H, PT1 :** Timer1 Interrupt Priority control. Definition as above.

B9h.2, B8h.2 **PX1H, PX1 :** External INT1 pin Interrupt Priority control. Definition as above.

B9h.1, B8h.1 **PT0H, PT0 :** Timer0 Interrupt Priority control. Definition as above.

B9h.0, B8h.0 **PX0H, PX0 :** External INT0 pin Interrupt Priority control. Definition as above.

BBh.7, BAh.7 **PI2CH, PI2C :** I2C Interrupt Priority control. Definition as above.

BBh.6, BAh.6 **PPWMH, PPWM :** PWM Interrupt Priority control. Definition as above.

BBh.5, BAh.5 **PLBDH, PLBD :** LBD Interrupt Priority control. Definition as above.

BBh.4, BAh.4 **PSPIH, PSPI :** SPI Interrupt Priority control. Definition as above.

BBh.3, BAh.3 **PADTKH, PADTK :** ADC / Touch Key Interrupt Priority control. Definition as above.

BBh.2, BAh.2 **PX2H, PX2 :** External INT2 pin Interrupt Priority control. Definition as above.

BBh.1, BAh.1 **PPNCH, PPNC :** Pin Change Interrupt Priority control. Definition as above.

BBh.0, BAh.0 **PT3H, PT3 :** Timer3 Interrupt Priority control. Definition as above.

6.2 Pin Interrupt & Wake up

Pin Interrupts include INT0 (P3.2), INT1 (P3.3), INT2 (P2.7) and Pin Change Interrupt. These pins also have the Stop/Halt mode wake up capability. INT0 and INT1 are falling edge or low level triggered as the 8051 standard. INT2 is falling edge triggered. Pin Change Interrupt is triggered by P1.7~0 / P3.7~4 / P3.1~0 / P2.5~4 pin state change.

Pin Interrupt & Wake up

95h.2 **IE2:** External Interrupt 2 (INT2 pin) edge flag

Set by H/W when a falling edge is detected on the INT2 pin, no matter the EX2 is 0 or 1. It is cleared automatically when the program performs the interrupt service routine. S/W can write FBh to INTFLG to clear this bit.

95h.1 **PNCIF:** Pin change interrupt flag Set by H/W when a Port1 \sim 3 pin state change is detected and its interrupt enable bit is set (P1WKUP) / P3WKUP). PNCIE does not affect this flag's setting. It is cleared automatically when the program performs the interrupt service routine. S/W can write FDh to INTFLG to clear this bit.

Note2: S/W can write 0 to clear a flag in the INTFLG, but writing 1 has no effect.

6.3 Idle mode Wake up and Interrupt

Idle mode is waked up by enabled Interrupts, which means individual interrupt enable bit (ex: EX0) and EA bit must be both set to 1 to establish Idle mode wake up capability. All enabled Interrupts (Pins, Timers, TK, SPI and UART) can wake up CPU from Idle mode. Upon Idle wake-up, Interrupt service routine is entered immediately. "The first instruction behind IDL (PCON.0) setting" is executed after interrupt service routine return.

EA=EX0=1, Idle mode wake-up and Interrupt by P3.2 (INT0)

87h.1 **PD:** Power down control bit, set 1 to enter Stop/Halt mode.

87h.0 **IDL:** Idle mode control bit, set 1 to enter Idle mode.

6.4 Halt/Stop mode Wake up and Interrupt

Halt/Stop mode wake up is simple, as long as the individual pin interrupt enable bit (ex: EX0) is set, the pin wake up capability is asserted. Set EX0/EX1/EX2 can enable INT0/INT1/INT2 pins' Halt/Stop mode wake up capability. Set P1WKUP/P3WKUP can enable Port1~3's Halt/Stop mode wake up capability. Upon Halt/Stop wake up, "the first instruction behind PD setting (PCON.1)" is executed immediately before Interrupt service. Interrupt entry requires EA=1 (Pin change also needs PNCIE=1) and trigger state of the pin staying sufficiently long to be sampled by the System clock. This feature allows CPU to enter or not enter Interrupt sub-routine after Halt/Stop mode wake up. Besides pin wakeup, PWM and Timer3 can also wakeup Halt mode if PWMIE/ET3 is set.

Note: Chip cannot enter Stop/Halt mode if INTn pin is low and wakeup is enable. (INTn=0 and EXn=1, n=0,1,2)

Note: It is recommended to place the NX1/NX2 with NOP Instruction in figures below.

7. I/O Ports

The chip has total 40 multi-function I/O pins. All I/O pins follow the standard 8051 "Read-Modify-Write" feature. The instructions that read the SFR rather than the Pin State are the ones that read a port or port bit value, possibly change it, and then rewrite it to the SFR. (ex: ANL P1, A; INC P2; CPL P3.0)

7.1 Port1 & Port3

These pins can operate in four different modes as below.

Port1, Port3 I/O Pin Function Table

If a Port1 or Port3 pin is used for Schmitt-trigger input, S/W must set the I/O pin to Mode0 or Mode1 and set the corresponding Port Data SFR to 1 to disable the pin's output driving circuitry.

Beside I/O port function, each Port1 and Port3 pin has one or more alternative functions, such as Touch Key, ADC, LCD, PWM and RFC. Port1/Port3 pins also have standard 8051 auxiliary definition such as INT0/1, T0/1/2, or RXD/TXD. These pin functions need to set the pin mode SFR to Mode0 or Mode1 and keep the P1.n / P3.n SFR at 1.

Port1, Port3 multi-function Table

The necessary SFR setting for Port1/Port3 pin's alternative functions is list below.

For tables above, a "**CMOS Output**" pin means it can sink and drive at least 4mA current. It is not recommended to use such pin as input function.

An "**Open Drain**" pin means it can sink at least 4mA current but only drive a small current (< 20uA). It can be used as input or output function and typically needs an external pull up resistor.

An 8051 standard pin is a "**Pseudo Open Drain**" pin. It can sink at least 4mA current when output is at low level, and drives at least 4mA current for $1~2$ clock cycle when output transits from low to high, then keeps driving a small current (< 20uA) to maintain the pin at high level. It can be used as input or output function.

P1.0 Pin Structure

90h.7~0 **P1:** Port1 data

B0h.7~0 **P3:** Port3 data

A5h.1~0 **P3MOD4:** P3.4 pin control. 00: Mode0 01: Mode1

10: Mode2

11: Mode3, P3.4 is ADC input

D7h.2 **PWM1OE:** PWM1 output to P3.5

- D7h.1 **PWM0POE:** PWM0P output to P3.7
- D7h.0 **PWM0NOE:** PWM0N output to P3.6

7.2 Port0, Port2 & Port4

These pins are shared with LCD, LED, I2C, SPI and crystal oscillator. If a Port0/2/4 pin is defined as I/O pin, it can be used as CMOS push-pull output or Schmitt-trigger input. The pin's pull up function is enable while SFR bit $PxOE.n=0$ and $Px.n=1$.

P2.6~P2.0 & Port0 I/O Pin Function Table

Port0, Port2 & Port4 multi-function Table

The necessary SFR setting for Port0/Port2/Port4 pin's alternative functions is list below.

80h.7~0 **P0:** Port0 data, also controls the P0.n pin's pull-up function. If the P0.n SFR data is "1" and the corresponding P0OE.n=0 (input mode), the pull-up is enabled.

A0h.7~0 **P2:** Port2 data, also controls the P2.n pin's pull-up function. If the P2.n SFR data is "1" and the corresponding P2OE.n=0 (input mode), the pull-up is enabled.

E8h.7~0 **P4:** Port4 data, also controls the P4.n pin's pull-up function. If the P4.n SFR data is "1" and the corresponding P4OE.n=0 (input mode), the pull-up is enabled.

91h.7~0 **P0OE:** Port0 CMOS Push-Pull output enable control, 1=Enable.

93h.7~0 **P2OE:** Port2 CMOS Push-Pull output enable control, 1=Enable.

A6h.7~0 **P4OE:** Port4 CMOS Push-Pull output enable control, 1=Enable.

D8h.4 **SCKTYPE:** Set 1 to enable P0.7 and P2.0 pin's SXT oscillation mode

Note: In crystal mode, user should set the P0.7/P2.0 (SXT) pins as Input with Pull-up.

AEh.7~4 **P4SEG:** Port4 LCD/LED mode control.

0000: P4.0~P4.7 are I/O pins 0001: P4.0~P4.6 are I/O pins, P4.7 is LCD/LED Segment pin 0010: P4.0~P4.5 are I/O pins, P4.6~P4.7 are LCD/LED Segment pins 0011: P4.0~P4.4 are I/O pins, P4.5~P4.7 are LCD/LED Segment pins 0100: P4.0~P4.3 are I/O pins, P4.4~P4.7 are LCD/LED Segment pins 0101: P4.0~P4.2 are I/O pins, P4.3~P4.7 are LCD/LED Segment pins 0110: P4.0~P4.1 are I/O pins, P4.2~P4.7 are LCD/LED Segment pins 0111: P4.0 is I/O pin, P4.1~P4.7 are LCD/LED Segment pins 1000: P4.0~P4.7 are LCD/LED Segment pins

D3h.7 **P07ADC:** P0.7 ADC pin select. 1=Select P0.7 as ADC input

D3h.6 **P20ADC:** P2.0 ADC pin select. 1=Select P2.0 as ADC input

D3h.5 **P02TCO:** P0.2 TCO pin select. 1=Select P0.2 as $F_{\text{SYSCLK}}/2$ output

D3h.2 **VBGOUT:** P1.1 VBG pin select. 1=Select P1.1 as VBG output

BCh.7 **SPEN:** SPI Enable.

0: SPI Disable

1: SPI Enable, P2.4~P2.6 are SPI functional pins.

E1h.7 **MIEN**:Master I2C enable

0: I2C Disable

1: I2C Enable, P0.0~P0.1 are I2C functional pins.

8. Timers

Timer0, Timer1 and Timer2 are provided as standard 8051 compatible timer/counter. Timer3 is provided for a real-time clock count.

8.1 Timer0 / Timer1 / Timer2

Compare to the traditional 12T 8051, the chip's Timer0/1/2 use 2 System clock cycle as the time base unit. That is, in timer mode, these timers increase at every "2 System clock" rate; in counter mode, T0, T1 and T2 pins' input pulse must be wider than 2 System clock to be sampled by this chip.

In addition to standard 8051 timers function, SLOWCLK/16 can replace P3.4(T0), P3.5(T1) and P1.0(T2) pins as the Timer0, Timer1 and Timer2 counter mode input. Timer0 also supports RFC counting. The RFC clock divided/gated signal can also replace T0 pin as the Timer0's event count input.

Timer0 and Timer1 structure

TCON and TMOD set the operation mode and control the running and interrupt generation of Timer0/1, with the timer/counter values stored in two pairs of 8-bit registers (TL0, TH0, and TL1, TH1).

8Ah.7~0 **TL0:** Timer0 data low byte

8Bh.7~0 **TL1:** Timer1 data low byte

8Ch.7~0 **TH0:** Timer0 data high byte

8Dh.7~0 **TH1:** Timer1 data high byte

Timer2 is controlled through the TCON2 register with the low and high bytes of Timer/Counter2 stored in TL2 and TH2 and the low and high bytes of the Timer2 reload/capture registers stored in RCAP2L and RCAP2H. Timer2 also supports SLOWCLK/16 event count mode.

Timer2 structure

CAh.7~0 **RCP2L:** Timer2 reload/capture data low byte

CBh.7~0 **RCP2H:** Timer2 reload/capture data high byte

CCh.7~0 **TL2:** Timer2 data low byte

CDh.7~0 **TH2:** Timer2 data high byte

AFh.5~4 **T0SEL:** Timer0 Counter mode (CT0N=1) input select

00: P3.4 pin (8051 standard)

01: RFC clock divided by 1/4/16/64

10: Slow clock divided by 16 (SLOWCLK/16)

11: RFC clock divided by 1/4/16/64 gated by Timer2 overflow

AFh.3~2 **RFCPSC:** RFC clock divider to Timer0

- 00: divided by 64
- 01: divided by 16
- 10: divided by 4
- 11: divided by 1

94h.1 **T2SEL:** Timer2 Counter mode (CT2N=1) input select 0: P1.0 pin (8051 standard) 1: Slow clock divided by 16 (SLOWCLK/16) 94h.0 **T1SEL:** Timer1 Counter mode (CT1N=1) input select 0: P3.5 pin (8051 standard) 1: Slow clock divided by 16 (SLOWCLK/16)

Note: for SLOWCLK/16 sampling, System clock must not be slower than SLOWCLK/4.

8.2 Timer3

The 23-bit wide Timer3 is reloadable for its 8-bit MSB when overflow. Its time base is Slow clock (SRC or SXT). Timer3 can generate interrupt periodically at different rate, and its counting data can be read out by CPU. It is recommended to read Timer3 data in Slow mode. While CPU clock is switched to Fast clock, the clock source of CPU and Timer3 are different, CPU may read a "under changing Timer3 data". User F/W must have some filter mechanism to avoid such kind un-stability. On the contrast, Timer3 interrupt has no ambiguous behavior no matter what the CPU clock source is.

Timer3 Structure

Timer3 can control its counting rate by the TM3ADJ SFR. This feature compensates the 32768 SXT crystal's in-accuracy. While TM3ADJ=0, Timer3 increase its data count normally at each Slow clock cycle. If TM3ADJ is set to positive adjustment, Timer3 increase its data count by 2 in particular Slow clock cycles, resulting a faster counting rate. If TM3ADJ is set to negative adjustment, Timer3 stop increase in particular Slow clock cycles, resulting a slower counting rate. The adjustment is 0.477ppm per step, and the total adjustable range is \pm 61ppm.

F8h.2 **CLRTM3:** Set 1 to Clear Timer3 and force TM3SEC reload

D2h.6~4 **TM3PSC:** Timer3 Interrupt rate

000: Timer3 interrupt occurs when 23 bit count data overflow

001: Timer3 interrupt rate is 32768 Slow clock cycles (1.0 second for SXT)

010: Timer3 interrupt rate is 16384 Slow clock cycles (0.5 second for SXT)

011: Timer3 interrupt rate is 8192 Slow clock cycles (0.25 second for SXT)

100: Timer3 interrupt rate is 4096 Slow clock cycles (0.125 second for SXT)

101: Timer3 interrupt rate is 2048 Slow clock cycles (62.5 ms for SXT)

110: Timer3 interrupt rate is 1024 Slow clock cycles (31.2 ms for SXT)

111: Timer3 interrupt rate is 512 Slow clock cycles (15.6 ms for SXT)

95h.0 **TF3:** Timer3 Interrupt Flag

Set by H/W when Timer3 reaches TM3PSC setting cycles. Cleared automatically when the program performs the interrupt service routine. S/W can write FEh to INTFLG to clear this bit. (*Note2*)

B3h.7~0 **TM3SEC:** Timer3 count data bit 22~15

B4h.7~0 **TM3DL:** Timer3 count data bit 7~0

B5h.6~0 **TM3DH:** Timer3 count data bit 14~8

B6h.7~0 **TM3RLD:** Timer3 overflow reload data for Timer3 bit 22~15 (TM3SEC)

B7h.7 **TM3ADJS:** Timer3 adjustment sign

0: Timer3 positive adjust, to increase Timer3 counting rate

1: Timer3 negative adjust, to decrease Timer3 counting rate

B7h.6~0 **TM3ADJ:** Timer3 adjust magnitude, 0.477 ppm per LSB.

The adjustment is calculated as \pm TM3ADJ*0.477ppm. The total adjustable range is \pm 61ppm.

Note6: also refer to Section 6 for more information about Timer0/1/2/3 Interrupt enable and priority.

9. UART

The UART uses SCON and SBUF SFRs. SCON is the control register, SBUF is the data register. Data is written to SBUF for transmission and SBUF is read to obtain received data. The received data and transmitted data registers are completely independent. In addition to standard 8051's full duplex mode, this chip also provides one wire mode. If the UART1W bit is set, both transmit and receive data use P3.1 pin. The chip also provide extra baud rate generator to save Timers loading. The RXD/TXD can be assigned to P3.0/P3.1 or P1.2/P1.3 pins.

SFR _{99h}	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SBUF	SBUF							
R/W	R/W							
Reset	$\overline{}$	$\qquad \qquad \qquad$	$\overline{}$	$\overline{}$	$\overline{}$	$\overbrace{}$	$\overline{}$	$\overline{}$

⁹⁹h.7~0 **SBUF:** UART transmit and receive data. Transmit data is written to this location and receive data is read from this location, but the paths are independent.

87h.7 **SMOD:** UART double baud rate control bit

0: Disable UART double baud rate

1: Enable UART double baud rate

C6h.7 **XBAUDS:** select UART extra baud rate generator

0: Baud rate uses Timer1/Timer2 overflow

1: Baud rate uses BAUDRT

C6h.6~0 **BAUDRT:** Extra baud rate

F_{SYSCLK} denotes System clock frequency, the UART baud rate is calculated as below.

Mode 0:

Baud Rate = $F_{\text{SYSCLK}}/2$

- Mode 1, 3: if using Timer1 auto reload mode Baud Rate = $(SMOD + 1)$ x F_{SYSCLK} / (32 x 2 x (256 – TH1))
- **Mode 1, 3:** if using Timer2 Baud Rate = Timer2 overflow rate / $16 = F_{SYSCLK}$ / (32 x (65536 – RCP2H, RCP2L))
- Mode 1, 3: if using BAUDRT Baud Rate = F_{SYSCLK} / (32 x BAUDRT)
- **Mode 2:** Baud Rate = $(SMOD + 1)$ x F_{SYSCLK} / 64

Note6: also refer to Section 6 for more information about UART Interrupt enable and priority. *Note8:* also refer to Section 8 for more information about how Timer2 controls UART clock.

10. Resistance to Frequency Converter (RFC)

The RFC module can build the RC oscillation circuitry with RFCX pin and RFC0R, RFC1R or RFC2R pins. Only one RC oscillation circuitry is active at a time. There are 2 methods to measure the RFC clock frequency. One is to set the RFC as the Timer0 Counter mode input, the other one is to set RFC as the System clock. Since SXT is a precise timing source, user can derive the RFC frequency by comparing the Timer's count data which running by RFC and SXT.

RFC Structure

The Timer0's event count input can be selected by T0SEL SFR. When T0SEL=3, the RFC clock is gated by Timer2's overflow period then go into the Timer0 for event counting. This function helps Timer0 to count the RFC clock with more accuracy by H/W automatically start and stop gating the RFC clock. The steps of this usage are described below.

- 1. Proper setting the PINMODE/RFCON SFR to setup the RFC oscillation circuitry.
- 2. CT0N=1 (Timer0 counter mode), CT2N=0 (Timer2 timer mode), T0SEL=3.
- 3. STPRFC=1, RFC gating is cleared and waiting for next Timer2 overflow to start
- 4. Clear Timer0, write TH2/TL2 with a data to accelerate Timer2 overflow (ex: FF00)
- 5. STPRFC=0, RFC starts, wait for next two Timer2 overflows.
- 6. The Timer0 counting the RFC clock only in between the two Timer2 overflows time slot.

RFC clock to Timer0, T0SEL=3

RFC clock to Timer₀. T0SEL=1

SFR F8h	Bit 7	Bit	Bit --	Bit 4	Bit 3	Bit 2	Bit 1	Bit
AUX1	$\hspace{0.1mm}-\hspace{0.1mm}$	$\overline{}$	◡	◡	W	к	STPRFC	DPSEL
R/W	$\hspace{0.1mm}-\hspace{0.1mm}$	$\overline{}$	W W	W R	W	R/W	R/W	R/W
Reset	$\overline{}$	$\overline{}$						

F8h.1 **STPRFC:** Set 1 to stop RFC clock oscillating

D8h.7~6 **FCKTYPE:** Fast clock type select, These bits can be changed only in Slow mode (SELFCK=0) 00: Fast clock is FRC

10: Fast clock is MRC

11: Fast clock is RFC, S/W must setup RFC oscillating circuitry before this setting.

11. LCD / LED Driver

The **LCD Driver** is capable of driving the LCD panel with $3~8$ Commons and maximum 45 Segments. The module can operate with or without pump. If LCDPUMP=0, no external component is required, VBAT and VLX pin should be tied together. If LCDPUMP=1, two 0.1uF capacitor should be placed at CUP1, CUP2 and VLX pin as the diagram below. In 1/3 Bias mode, the VCLD voltage has 16 brightness levels, which is controlled by LCDBV SFR. The VL1 and VL2 voltage level are divided from VLCD. So VL1=VLCD/3, VL2=VLCD*2/3 and VL3=VLCD. In $1/2$ Bias mode, VL1=V_{BAT}=VLCD/2 and VL2=VLCD.

The VL1, VL2 and VLCD (VL3) LCD 1/3 bias voltage are generated by tenx's unique tiny current LCD Buffer technology, which can drive very big LCD panel without waveform distortion, but the Driver itself only consumes small current (1.6uA $@V_{BAT}=3V$). This technique also reduce external component and pin connection for package/PCB cost reduction.

Note: User must force LCDBV=1111b at least 100ms for 1/3 Bias pump mode start-up.

Table below illustrates VLCD and VL1 voltage for 1/3 Bias mode, with or without pump. User can detect the V_{BAT} voltage level by LBD, and accordingly set the LCDBV for VLCD voltage (brightness level).

LCD Brightness level setting by LCDBV

The LCD clock can be driven by Slow clock or Fast clock. If SXT is the clock source, the LCD frame rate ranges from 43 Hz to 98 Hz according to LCD Duty and LCDFRM. If the LCD clock comes from other clock source, the Frame rate varies proportionally to the clock frequency. The frame rate of LED mode is double of LCD mode in the same setting. The LED and LCD module share the same LCD RAM and several common SFR.

LCD Frame	LCDFMR (SFR B1h.1~0)						
Rate (Hz)	0 ⁰	01	10				
$1/3$ Duty	57	68	85	98			
$1/4$ Duty	43	51	64	73			
$1/5$ Duty	46	59	68	82			
$1/6$ Duty	57	68	85	98			
$1/7$ Duty	49	59	73	84			
$1/8$ Duty	43	51	64				

LCD Frame Rate when LCDCLK=SXT

In **LED Normal mode**, the chip provides maximum 8COM x 36SEG driver. For LED application, the COM pin is active low with dead time control and the Segment pin is active high. Each COM pin can sink 70mA current when $V_{BAT}=5V$. The chip support All LED Segment mode for DC output. In such application, user set LCDUTY=7 and fill the LCDRAM SEG bit with same data. For example, write 0xF001 with 0x00 for SEG1's low level output; write 0xF009 with 0xFF for SEG9's high level output.

Note: User must force LCDBV=1111b at least 100ms for 1/3 Bias pump mode start-up.

AEh.7~4 **P4SEG:** Port4 LCD/LED mode control.

0000: P4.0~P4.7 are I/O pins 0001: P4.0~P4.6 are I/O pins, P4.7 is LCD/LED Segment pin 0010: P4.0~P4.5 are I/O pins, P4.6~P4.7 are LCD/LED Segment pins 0011: P4.0~P4.4 are I/O pins, P4.5~P4.7 are LCD/LED Segment pins 0100: P4.0~P4.3 are I/O pins, P4.4~P4.7 are LCD/LED Segment pins 0101: P4.0~P4.2 are I/O pins, P4.3~P4.7 are LCD/LED Segment pins 0110: P4.0~P4.1 are I/O pins, P4.2~P4.7 are LCD/LED Segment pins 0111: P4.0 is I/O pin, P4.1~P4.7 are LCD/LED Segment pins 1000: P4.0~P4.7 are LCD/LED Segment pins

LCD / LED Normal mode RAM Mapping (8051's External Data Memory space)

LCD Waveform, 1/3 Bias, 1/4 Duty, (VLCD=3*VL1)

The chip also provides **LED DMX mode** (Dot Matrix mode) using COM0~COM7 pins, up to 7 * 8 = 56 LED points can be configured to drive. This mode is enabled by set LCDPUMP=1. The corresponding LED dot matrix position is marked in the figure below. The relationship between LRAM's bit and LED lighting map is also shown as below table.

LED DMX mode bit mapping

12. PWM

The chip has 6 channel CMOS output PWMs. Each PWM can select Fast clock or Slow clock as its clock source, with divided by $1~128$ prescaler. The PWM period is adjustable by PWMnPRD SFR and its 256 duty cycle controlled by PWMnDTY SFR. The PWM0P and PWM0N are positive and negative pairs, which support pump voltage drive. The PWM1 can sink maximum 300mA for IR application. The PWM5 can generate interrupt and wake-up CPU from Idle/Halt mode.

9Ah.7~0 **PWM0PRD:** PWM0 Period, FFh=256 PWMCLK, 7Fh=128 PWMCLK

9Bh.7~0 **PWM0DTY:** PWM0 Duty, 0=0 PWMCLK, 80h=128 PWMCLK, FFh=255 PWMCLK

9Ch.7~0 **PWM1PRD:** PWM1~4 Period, FFh=256 PWMCLK, 7Fh=128 PWMCLK

9Dh.7~0 **PWM1DTY:** PWM1 Duty, 0=0 PWMCLK, 80h=128 PWMCLK, FFh=255 PWMCLK

9Eh.7~0 **PWM2DTY:** PWM2 Duty, 0=0 PWMCLK, 80h=128 PWMCLK, FFh=255 PWMCLK

9Fh.7~0 **PWM3DTY:** PWM3 Duty, 0=0 PWMCLK, 80h=128 PWMCLK, FFh=255 PWMCLK

D4h.7~0 **PWM4DTY:** PWM4 Duty, 0=0 PWMCLK, 80h=128 PWMCLK, FFh=255 PWMCLK

D6h.7~0 **PWM5PRD:** PWM5 Period, FFh=256 PWMCLK, 7Fh=128 PWMCLK

D7h.7 **PWM5OE:** PWM5 output to P1.3

D7h.6 **PWM4BOE:** PWM4 output to P3.6

- D7h.5 **PWM4AOE:** PWM4 output to P1.1
- D7h.4 **PWM3OE:** PWM3 output to P1.0
- D7h.3 **PWM2OE:** PWM2 output to P3.4
- D7h.2 **PWM1OE:** PWM1 output to P3.5
- D7h.1 **PWM0POE:** PWM0P output to P3.7
- D7h.0 **PWM0NOE:** PWM0N output to P3.6

95h.3 **PWMIF:** PWM5 period counter full interrupt flag.

Set by H/W when PWM5 period counter full. Cleared automatically when the program performs the interrupt service routine. S/W can write F7h to INTFLG to clear this bit. (*Note2*)

13. Touch Key

The Touch Key module offers an easy, simple and reliable method to implement finger touch detection. The chip support 10 channels touch key detection.

Touch Key Structure

While a TK pin is under scanning, the module automatically disables the pin's CMOS output path. Therefore, user can set the scan TK pin's mode as Mode2. After TK scan, user must set TKPD=1 to disconnect the TK module and IO pins.

To start a TK scan, user assigns TKPD=0, then set the TKSOC bit to start touch key conversion. After the end of conversion, H/W clears the TKSOC bit and set the TKIF interrupt flag. However, if the SYSCLK is too slow, H/W might fail to clear TKSOC due to clock sampling rate. TKEOC=0 means conversion is in process. TKEOC=1 means the conversion is finish, and the touch key counting result is stored into the 14 bits TK Data Counter TKDH and TKDL. The larger TK pin capacitance is, the smaller TK Data counter is.

The Touch Key unit has an internal built-in reference capacitor to simulate the KEY behavior. Set TKCHS=15 and start a scan can get the TK Data count of this capacitor. Since the internal capacitor would not be affected by water or mobile phone, it is useful for comparing the environment background noise.

F8h.5 **TKSOC:** Rising edge of this bit will trigger a Touch Key conversion. Basically, this bit is automatically cleared by H/W after end of conversion. However, if the SYSCLK is too slow, H/W might fail to clear TKSOC due to clock sampling rate issue.

Reset 1 0 0 0 0 0 0 0 0 0 AEh.3~0 **TKREFC:** Touch Key reference clock capacitor select 0000: Smallest (conversion time shortest)

R/W R/W R/W

…

1111: Biggest (conversion time longest)

ABh.7 **TKEOC:** Touch Key End of Conversion, 1=EOC. TKEOC may have 3uS delay after TKSOC=1. ABh.5~0 **TKDTH:** Touch Key Counter Data 13~8

ACh.7~0 **TKDL:** Touch Key Counter Data 7~0

95h.5 **TKIF:** Touch Key Interrupt Flag

Set by H/W when TK end of conversion. S/W can write DFh to INTFLG to clear this bit.

Note6: also refer to Section 6 for more information about Touch Key Interrupt enable and priority.

14. 12-bit SAR ADC

The chip offers a 12-bit ADC consisting of analog input multiplexer, control register, clock generator, 12-bit successive approximation register, and output data register. To use the ADC, set the ADCKS bit first to choose a proper ADC clock frequency, which must be less than 2 MHz. Then, launch the ADC conversion by setting the ADSOC bit, and H/W will automatic clear it at the end of the conversion. After the end of the conversion, H/W will set the ADIF bit and generate an interrupt if an ADC interrupt is enabled. The ADIF bit can be cleared by writing 0 to this bit or 1 to the ADSOC bit. The V_{REF} of the ADC can be selected V_{BAT} or 2.4V.

F8h.4 **ADSOC:** Rising edge of this bit will trigger an ADC conversion. This bit is automatically cleared by H/W after end of conversion. S/W can also write 0 to clear this flag.

C5h.7~0 **ADDTH:** ADC data bit 11~4

C3h.4 **ADEOC:** ADC end of conversion. 1=end

C3h.3~0 **ADCDTL:** ADC data bit 3~0

95h.4 **ADIF:** ADC Interrupt Flag

Set by H/W when ADC end of conversion. S/W can write EFh to INTFLG to clear this bit.

Note: FW must force ADCSRV=0 before enter Stop/Halt/Idle mode.

15. Serial Peripheral Interface (SPI)

The SPI module is capable of full-duplex, synchronous, serial communication between the chip and peripheral devices. The peripheral devices can be other MCUs, A/D converter, sensors, or MTP memory, etc. The SPI runs at a baud rate up to the system clock divided by two. Firmware can read the status flags, or the operation can be interrupt driven.

The features of the SPI module include:

- Master or Slave mode operation
- 3-wire mode operation
- Full-duplex operation
- Programmable transmit bit rate
- Single Buffer receive
- Serial clock phase and polarity options
- MSB-first or LSB-first shifting selectable

SPI System Block Diagram

The MOSI (P2.4) signal is an output when SPI is operating in Master mode and an input when SPI is operating in Slave mode. The MISO (P2.6) signal is an input when SPI is operating in Master mode and an output when SPI is operating in Slave mode. Data is transferred MSB or LSB first by setting the LSBF bit. The SCK (P2.5) signal is an output from a Master device and an input to Slave devices. It is used to synchronize the data on the MOSI and MISO lines of Master and Slave. SPI generates the signal with eight programmable clock rates in Master mode.

Master Mode

The SPI operates in Master mode by setting the MSTR bit in the SPCON. To start transmit, writing a data to the SPDAT. If SPBSY=0, the data will be transferred to the shift register and starts shift out on the MOSI line. The data of the Slave shift in from the MISO line at the same time. When the SPIF bit becomes set at the end of transfer, the receive data is written to receiver buffer and the RCVBF bit in the SPSTA is set. To prevent an overrun condition, software must read the SPDAT before next byte enters the shift register. The SPBSY bit will be set when writing a data to SPDAT to start transmit, and be cleared at the end of the eighth SCK period in Master mode.

Slave Mode

The SPI operates in Slave mode by clearing the MSTR bit in the SPCON. The transmission will start when the SPEN bit in the SPCON is set. The data from a Master will shift into the shift register through the MOSI line, and shift out from the shift register on the MISO line. When a byte enters the shift register, the data will be transferred to receiver buffer if RCVBF=0. If RCVBF=1, the newer received data will not be transferred to receiver buffer and the RCVOVF bit is set. After a byte enters the shift register, the SPIF and RCVBF bits are set. To prevent an overrun condition, software must read the SPDAT or write 0 to RCVBF before next byte enters the shift register. The maximum SCK frequency allowed in Slave mode is $F_{\text{SYSCLK}}/4$.

Serial Clock

The SPI has four clock types by setting the CPOL and CPHA bits in the SPCON register. The CPOL bit defines the level of the SCK in SPI idle state. The level of the SCK in idle state is low when CPOL=0, and is high when CPOL=1. The CPHA bit defines the edges used to sample and shift data. The SPI sample data on the first edge of SCK period and shift data on the second edge of SCK period when CPHA=0. The SPI sample data on the second edge of SCK period and shift data on first edge of SCK period when CPHA=1. Figures below show the detail timing in Master and Slave modes. Both Master and Slave devices must be configured to use the same clock type before the SPEN bit is set. The SPCR controls the Master mode serial clock frequency. This register is ignored when operating in Slave mode. The SPI clock can select System clock divided by 2, 4, 8, or 16 in Master mode.

SPEN								
SPDAT_WR								
SCK $(CPOL=0, CPHA=0)$								
SCK $(CPOL=1, CPHA=0)$								
SCK $(CPOL=0, CPHA=1)$								
SCK $(CPOL=1, CPHA=1)$								
MOSI $(LSBF=0)$	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
MISO $(LSBF=0)$	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SPBSY								

Master Mode Timing

Slave Mode Timing (CPHA=0)

Slave Mode Timing (CPHA=1)

In both Master and Slave modes, the SPIF interrupt flag is set by H/W at the end of a data transfer. If write data to SPDAT when SPBSY=1, the WCOL interrupt flag will be set by H/W. When this occurs, the data write to SPDAT will be ignored, and shift register will not be written.

 $11:$ $F_{SYSCLK}/16$

Set by H/W when a SPI transfer is in progress.

BEh.7~0 **SPDAT:** SPI Transmit and Receive Data

The SPDAT register is used to transmit and receive data. Writing data to SPDAT place the data into shift register and start a transfer when in Master mode. Reading SPDAT returns the contents of the receive buffer.

Note6: also refer to Section 6 for more information about SPI Interrupt enable and priority. *Note7*: also refer to Section 7 for more information about SPI pins share with I/O pins

16. Master I ²C Interface

Master I²C interface transmit mode:

At the beginning write slave address and direction bit to MIDAT and set MISTART. After the START condition (MISTART), the 7 bits slave address and one bit direction bit are sent. When MIIF convert to 1, address and direction bit transmission was complete. After sending the address and direction bit, user should clear MIIF and write MIDAT to start first data transmission. When MIIF convert to 1, data transfer to slave was complete. User can write MIDAT again to transfer next data to slave. Set MISTOP to finish transmit mode.

MISTART must remain at 1 for the next transfer. After the final data transmit/receive, set MISTOP to finish transmit/receive protocol. MISTART should remain 0 longer than a MSCL clock before starting the next Master I^2C protocol. MSCL clock can be adjusted via MICR.

Master I²C Transmit flow:

- (1) Write slave address and direction bit to MIDAT
- (2) Clear MISTOP and set MISTART to start I²C transmission
- (3) Wait until MIIF convert to 1 (interrupt will be issued according to the user's request) and Clear MIIF
- (4) Write data to MIDAT to start next transfer (MISTART must remain at 1)
- (5) Wait until MIIF convert to 1 (interrupt will be issued according to the user's request) and Clear MIIF, Loop (4) ~ (5) for next transfer.
- (6) Clear MISTART and set MISTOP to stop the I²C transfer

Note: MISTART should remain 0 longer than a MSCL period before starting the next Master I²C protocol.

Master I²C interface Receive mode:

At the beginning write slave address and direction bit to MIDAT and set MISTART. After the START condition (MISTART), the 7 bits slave address and one bit direction bit are sent. When MIIF convert to 1, address and direction bit transmission was complete. After sending the address and direction bit, user should clear MIIF and read MIDAT to start first receive data (The first reading of MIDAT does not represent the data returned by the slave). When MIIF convert to 1, data receive from slave was complete. User can read MIDAT to get data from slave, and start next receive. Set MISTOP to finish receive mode.

MISTART must remain at 1 for the next transfer. After final data transmit/receive, set MISTOP to finish transmit/receive protocol. MISTART should remain 0 longer than a MSCL clock before starting the next Master I²C protocol. MSCL clock can be adjusted via MICR.

Master I²C Receive flow:

- (1) Write slave address and direction bit to MIDAT
- (2) Clear MISTOP and set MISTART to start I $\mathcal X$ transmission
- (3) Wait until MIIF convert to 1 (interrupt will be issued according to the user's request)
- (4) Clear MIIF
- (5) Read data from MIDAT to start first receive data (The first reading of MIDAT does not represent the data returned by the slave)
- (6) Wait until MIIF convert to 1
- (7) Clear MIIF
- (8) Read slave data from MIDAT and receive next data
- (9) Loop $(6) \sim (8)$
- (10) Set MISTOP to stop the I²C transfer

Note: MIDAT 25h and A6h are data from slave

Note: MISTART should remain 0 longer than a SCL clock before starting the next Master I²C Transfer protocol

E2h.7~0 **MIDAT**: Master I²C data shift register

(W): After Start and before Stop condition, write this register will resume transmission to $I²C$ bus (R): After Start and before Stop condition, read this register will resume receiving from I^2C bus

17. Cyclic Redundancy Check (CRC)

The chip supports an integrated 16-bit Cyclic Redundancy Check function. The Cyclic Redundancy Check (CRC) calculation unit is an error detection technique test algorithm and uses to verify data transmission or storage data correctness. The CRC calculation takes a 8-bit data stream or a block of data as input and generates a 16-bit output remainder. The data stream is calculated by the same generator polynomial.

CRC Block Diagram

The CRC generator provides the 16-bit CRC result calculation based on the CRC-16-IBM polynomial. In this CRC generator, there are only one polynomial available for the numeric values calculation. It can't support the 16-bit CRC calculations based on any other polynomials. Each write operation to the CRCIN register creates a combination of the previous CRC value stored in the CRCDH and CRCDL registers. It will take one MCU instruction cycle to calculate.

CRC-16-IBM (Modbus) Polynomial representation: $X^{16} + X^{15} + X^2$

F1h.7~0 **CRCDL:** 16-bit CRC checksum data bit 7~0

F2h.7~0 **CRCDL:** 16-bit CRC checksum data bit 15~8

F3h.7~0 **CRCIN:** CRC input data register

18. In Circuit Emulation (ICE) Mode

The chip can support the In Circuit Emulation mode. To use the ICE Mode, user just needs to connect P1.2 and P1.3 pin to the tenx proprietary EV module. The benefit is that user can emulate the whole system without changing the on board target device. But there are some limits for the ICE mode as below.

- 1. The chip must be un-protect.
- 2. The chip's P1.2 and P1.3 pins must work in input Mode (P1MOD2=0/1 and P1MOD3=0/1).
- 3. The Program ROM's addressing space 2D00h~2FFFh and 0033h~003Ah are occupied by tenx EV Module. So user Program cannot access these spaces.
- 4. The P1.2 and P1.3 pin's function cannot be emulated.

ICE Mode Connection

SFR & CFGW MAP

SFR & CFGW DESCRIPTION

INSTRUCTION SET

Instructions are 1, 2 or 3 bytes long as listed in the 'byte' column below. Each instruction takes 1~8 System clock cycles to execute as listed in the 'cycle' column below.

In the above table, an entry such as E8-EF indicates a continuous block of hex opcodes used for 8 different registers, the register numbers of which are defined by the lowest three bits of the corresponding code. Non-continuous blocks of codes, shown as 11-F1 (for example), are used for absolute jumps and calls with the top 3 bits of the code being used to store the top three bits of the destination address.

ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

DC **Characteristics (TA=25°C)**

Operation Voltage (V_{DD}) (T_A=25°C)

ADC, BandGap & POR Characteristics

Clock Timing (TA=25°C)

EEPROM Characteristics

Note: The value of above parameter is based on the characteristics of tested samples.

Characteristic Graphs

DS-TM52F2384_E 97 **Rev 1.4, 2024/7/3**

Note: Since LVR and LVD are derived from VBG, they have the same characteristic as VBG.

Note: The value of above curve is based on the characteristics of tested samples. *It does not mean all chips have the same characteristic.*

PACKAGE INFORMATION

Please note that the package information provided is for reference only. Since this information is frequently updated, users can contact Sales to consult the latest package information and stocks.

Ordering Information

Package Information

LQFP-48 (7×7mm) Package Dimension

 \mathbb{A} * NOTES : DIMENSION "D1" AND "E1" DO NOT INCLUDE MOLD

PROTRUSIONS. ALLOWABLE PROTRUSIONS IS 0.25 mm PER SIDE. $^{\circ}$ D1 $^{\prime}~$ AND $\,^{\circ}$ E1 $^{\prime}~$ ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMACH.

LQFP-64 (7×7mm) Package Dimension

 $\mathbb A$ * NOTES : DIMENSION * D1 * AND * E1 * DO NOT INCLUDE MOLD

PROTRUSIONS. ALLOWABLE PROTRUSIONS IS 0.25mm PER SIDE. $\,$ $\,^\circ$ D1 $\,^\prime\,$ AND $\,$ $\,$ E1 $\,^\prime\,$ ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS

INCLUDING MOLD MISMACH.

QFN-48 (6×6mm) Package Dimension

